



Seiko Seiki STP-H803, H1303

Technical Specifications

Item		H803 Series	H1303 Series
Flange size	Inlet port flange	VG150/ISO160	VG200/ISO200
	Outlet port flange	KF40	KF40
Pumping speed	N ₂	800 L/s	1300
	H ₂	600 L/s	1000
Compression ratio	N ₂	>10 ⁸	
	H ₂	10 ⁴	
Ultimate pressure	Pa (Torr)	10 ⁻⁷ (10 ⁻⁹) order (after baking)	
Maximum working pressure ^{*1}	Pa (Torr)	13.3 (0.1): Water cooling	
Allowable backing pressure ^{*1}	Pa (Torr)	270 (2): Water cooling	
Rated speed	rpm	32,500	
Starting time	min	7	
Stopping time	min	8	
Noise	dB	<50 (at 32,500 rpm)	
Baking temperature	°C	<120	
Lubricating oil		Not necessary	
Installation position		Free	
Cooling method		Water cooling	
Standard backing pump	L/min	>1,300	
Mass ^{*2}	kg	39	
Dimensions	mm	Φ 270×H343(VG150) Φ 270×H350(ISO160F)	Φ 270×H312
Ambient temperature range	°C	0 to 40	
Storage temperature range	°C	- 25 to + 55	

The values shown in the table are typical.; They are not guaranteed.

^{*1}: The pressure is applicable under conditions that N₂ or other similar gas is vacuumed and the backing pump (pumping speed: 1,300 L/min) is used.

^{*2}: Mass is a value of state that the only standard accessory was installed (except the optional accessory).



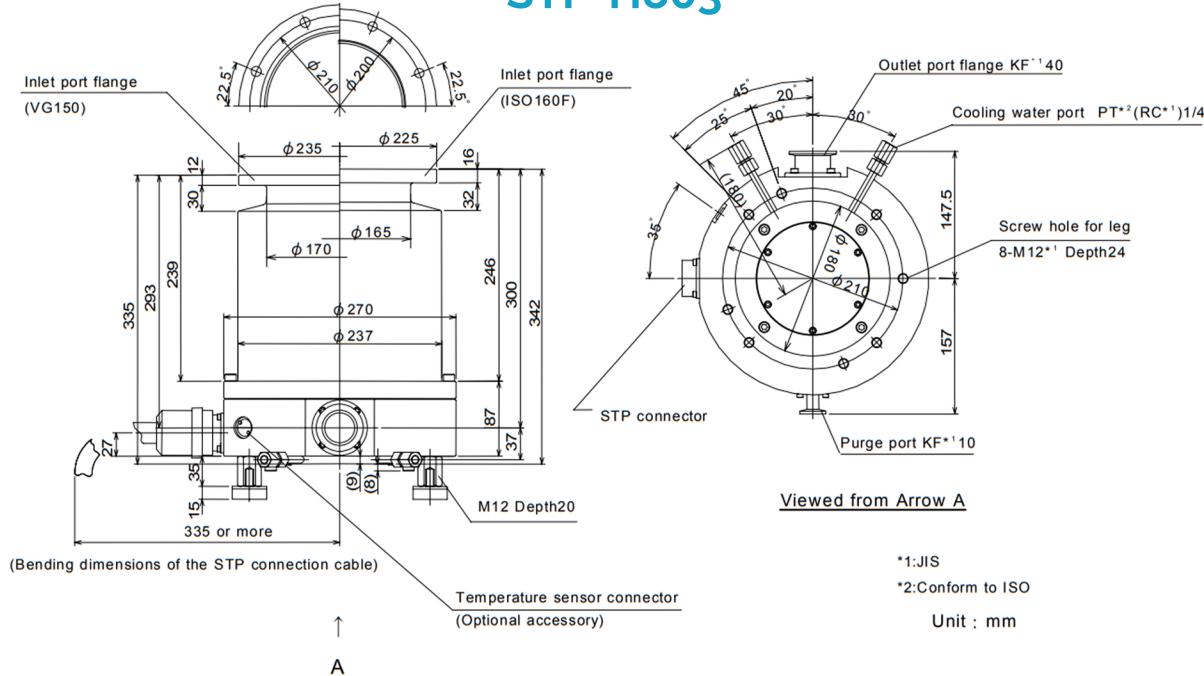
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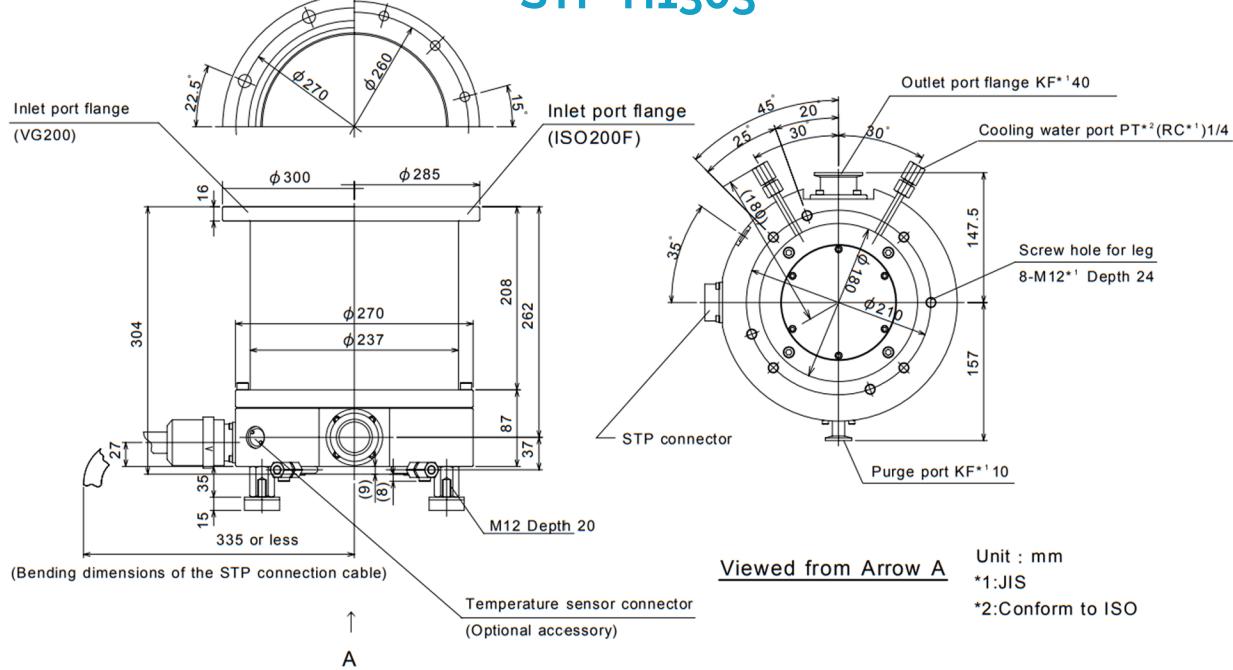
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Dimensions

STP-H803



STP-H1303





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Features & Benefits

- oil free
- low vibration
- high reliability
- maintenance free
- increased life
- advanced controller design
- compact design
- small footprint
- advanced rotor technology
- installation in any orientation

Applications

- plasma etch • ECR etch • film deposition • sputtering • ion implantation source • beam line pumping • MBE • diffusion • photo resist stripping
- crystal / epitaxial growth • wafer inspection • load lock chambers

Recommended controller

- controllers: SCU-750 • SCU-800